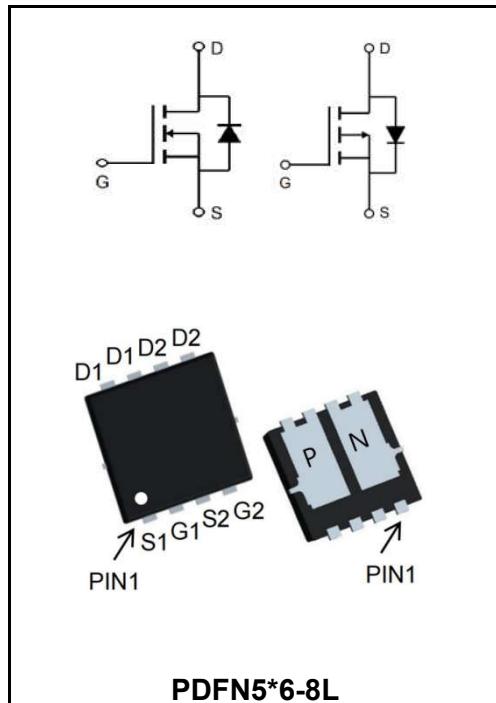


40V N+P-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	23A
V_{DSS}	40V
$R_{DS(ON)}\text{-typ}(@V_{GS}=10V)$	<19mΩ (Typ:14 mΩ)
$R_{DS(ON)}\text{-typ}(@V_{GS}=4.5V)$	<24mΩ (Typ:18 mΩ)
I_D	-20A
V_{DSS}	-40V
$R_{DS(ON)}\text{-typ}(@V_{GS}=-10V)$	<30mΩ (Typ:20 mΩ)
$R_{DS(ON)}\text{-typ}(@V_{GS}=-4.5V)$	<40mΩ (Typ:28 mΩ)


DESCRIPTION

The YFW23G04NF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application

APPLICATION

- Wireless charging
- Boost driver
- Brushless motor

Maximum Ratings at $T_c=25^\circ C$ unless otherwise specified

Characteristics	Symbols	Value		Units
		N-Ch	P-Ch	
Drain-Source Voltage	V_{DS}	40	-40	V
Gate - Source Voltage	V_{GS}	± 20	± 20	V
Continuous Drain Current, $V_{GS} @ 10V^1 @ T_c=25^\circ C$	I_D	23	-20	A
Continuous Drain Current, $V_{GS} @ 10V^1 @ T_c=100^\circ C$	I_D	18	-16	A
Pulsed Drain Current ²	I_{DM}	46	-40	A
Single Pulse Avalanche Energy ³	E_{AS}	28	66	mJ
Avalanche Current	I_{AS}	17.8	-27.2	A
Total Power Dissipation ⁴ @ $T_c=25^\circ C$	P_D	25	31.3	W
Storage Temperature Range	T_{STG}	-55 to +150	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	-55 to +150	°C
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	62		°C/W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	5		°C/W

N-Channel Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	$V(BR)DSS$	40	-	-	V
BV _{DSS} Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$, $I_D=1\text{mA}$	$\Delta BV_{DSS}/\Delta T_J$	-	0.032	-	V/ $^{\circ}\text{C}$
Static Drain-Source On-Resistance note ²	$V_{GS}=10\text{V}$, $I_D=15\text{A}$	$R_{DS(ON)}$	-	14	19	m Ω
	$V_{GS}=4.5\text{V}$, $I_D=10\text{A}$		-	18	24	m Ω
Gate -Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	$V_{GS(th)}$	1.0	1.7	2.5	V
$V_{GS(th)}$ Temperature Coefficien		$\Delta V_{GS(th)}$	-	-4.8	-	mV/ $^{\circ}\text{C}$
Drain-Source Leakage Current	$V_{DS}=32\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	I_{DSS}	-	-	1	μ A
	$V_{DS}=32\text{V}$, $V_{GS}=0\text{V}$, $T_J=55\text{ }^{\circ}\text{C}$		-	-	5	
Gate to Body Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	I_{GSS}	-	-	± 100	n A
Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=15\text{A}$	g_{fs}	-	34	-	S
Gate Resistance	$V_{DS}=0\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	R_g	-	2.1	-	Ω
Total Gate Charge(4.5V)	$V_{DS}=32\text{V}$ $V_{GS}=4.5\text{V}$ $I_D=15\text{A}$	Q_g	-	10	-	n C
Gate-Source Charge		Q_{gs}	-	2.55	-	
Gate-Drain Charge		Q_{gd}	-	4.8	-	
Turn-on delay time	$V_{DD}=20\text{V}$ $V_{GS}=10\text{V}$ $R_G=3.3\Omega$ $I_D=15\text{A}$	$t_{d(on)}$	-	2.8	-	ns
Turn-on Rise Time		T_r	-	12.8	-	
Turn-Off Delay Time		$t_{d(OFF)}$	-	21.2	-	
Turn-on Fall Time		t_f	-	6.4	-	
Input Capacitance	$V_{DS}=15\text{V}$ $V_{GS}=0\text{V}$ $f=1.0\text{MHz}$	C_{iss}	-	1013	-	p F
Output Capacitance		C_{oss}	-	107	-	
Reverse Transfer Capacitance		C_{rss}	-	76	-	
Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Curren	I_s	-	-	23	A
Pulsed Source Current ^{2,5}		I_{SM}	-	-	46	A
Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_S=1\text{A}$ $T_J=25\text{ }^{\circ}\text{C}$	V_{SD}	-	-	1.2	V
Reverse Recovery Time	$I_F=15\text{A}, dI/dt=100\text{A}/\mu\text{s}$, $T_J=25\text{ }^{\circ}\text{C}$	trr	-	10	-	nS
Reverse Recovery Charge		Qrr	-	3.1	-	nS

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is $V_{DD}=25\text{V}$, $V_{GS}=10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=25\text{A}$
- 4、The power dissipation is limited by $150\text{ }^{\circ}\text{C}$ junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu\text{A}$	$V(BR)DSS$	-40	-	-	V
BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1\text{mA}$	$\Delta \text{BV}_{DSS}/\Delta T_J$	-	-0.012	-	mV/^\circ\text{C}
Static Drain-Source On-Resistance note ²	$V_{GS}=-10V, I_D=-5\text{A}$	$R_{DS(\text{ON})}$	-	20	30	m\Omega
	$V_{GS}=-4.5V, I_D=-3.5\text{A}$		-	28	40	m\Omega
Gate -Threshold Voltage	$V_{GS}=V_{DS}, I_D =-250\mu\text{A}$	$V_{GS(\text{th})}$	-1.0	-1.6	-2.5	V
$V_{GS(\text{th})}$ Temperature Coefficien		$\Delta V_{GS(\text{th})}$		4.32	-	mV/^\circ\text{C}
Drain-Source Leakage Current	$V_{DS}=-32V, V_{GS}=0V, T_J=25^\circ\text{C}$	I_{DSS}	-	-	1	\mu\text{A}
	$V_{DS}=-32V, V_{GS}=0V, T_J=55^\circ\text{C}$		-	-	5	
Gate to Body Leakage Current	$V_{GS}=\pm20V, V_{DS}=0V$	I_{GSS}	-	-	± 100	nA
Forward Transconductance	$V_{DS}=-5V, I_D=-8\text{A}$	g_{fs}	-	12.6	-	S
Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	R_g		13	16	\Omega
Total Gate Charge (-4.5V)	$V_{DS}=-20V$ $V_{GS}=-4.5V$ $I_D=-12\text{A}$	Q_g	-	9	-	nC
Gate-Source Charge		Q_{gs}	-	2.54	-	
Gate-Drain Charge		Q_{gd}	-	3.1	-	
Turn-on delay time	$V_{DD}=-15V$ $V_{GS}=-10V$ $R_g=3.3\Omega$ $I_D=-1\text{A}$	$t_{d(on)}$	-	19.2	-	ns
Turn-on Rise Time		T_r	-	12.8	-	
Turn-Off Delay Time		$t_{d(OFF)}$	-	48.6	-	
Turn-on Fall Time		t_f	-	4.6	-	
Input Capacitance	$V_{DS}=-15V$ $V_{GS}=0V$ $f=1\text{MHz}$	C_{iss}	-	1004	-	pF
Output Capacitance		C_{oss}	-	108	-	
Reverse Transfer Capacitance		C_{rss}	-	80	-	
Continuous Source Current ^{1,5}	$V_G=V_D=0V$, Force Curren	I_s	-	-	-20	A
Pulsed Source Current ^{2,5}		I_{SM}	-	-	-40	A
Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=-1\text{A} T_J=25^\circ\text{C}$	V_{SD}	-	-	-1	V

Note :

1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

3.The EAS data shows Max. rating . The test condition is $VDD=-25V, VGS=-10V, L=0.1\text{mH}, IAS=-27.2\text{A}$

4.The power dissipation is limited by 150°C junction temperature

5 .The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

N-Typical Characteristics

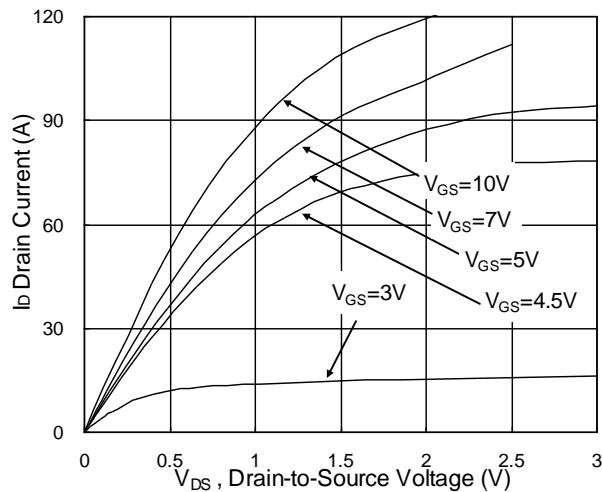


Fig.1 Typical Output Characteristics

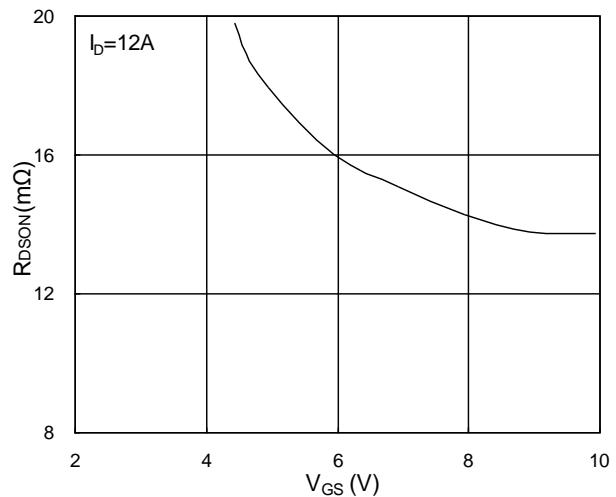


Fig.2 On-Resistance vs. G-S Voltage

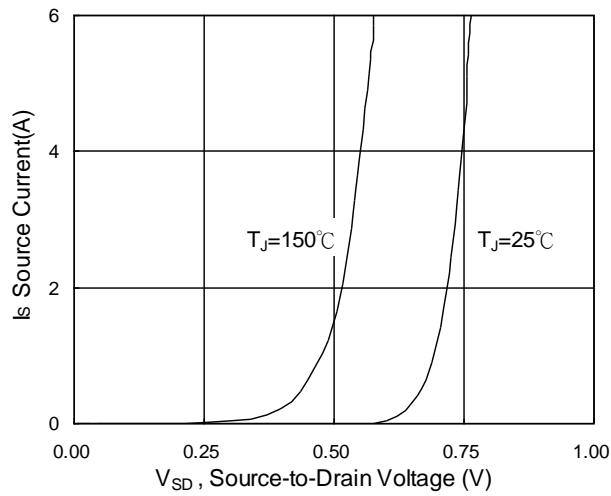


Fig.3 Forward Characteristics of Reverse

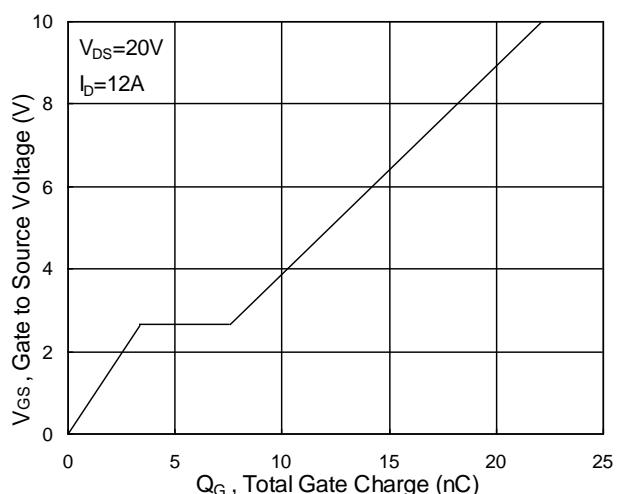


Fig.4 Gate-Charge Characteristics

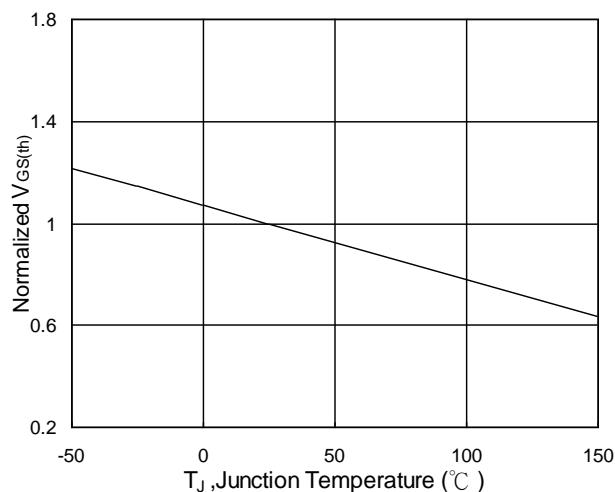


Fig.5 $V_{GS(th)}$ vs. T_J

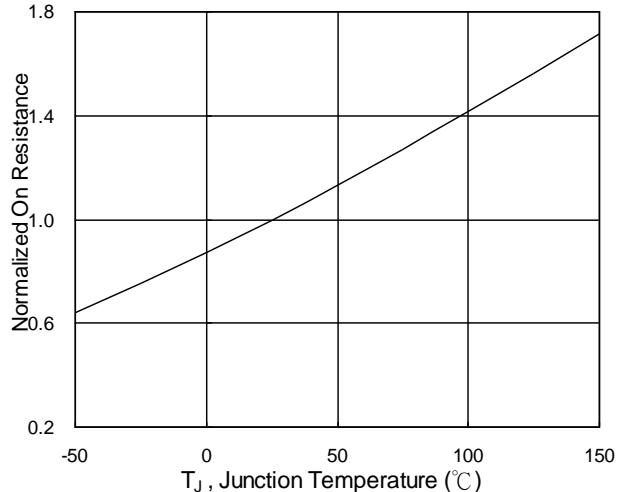


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

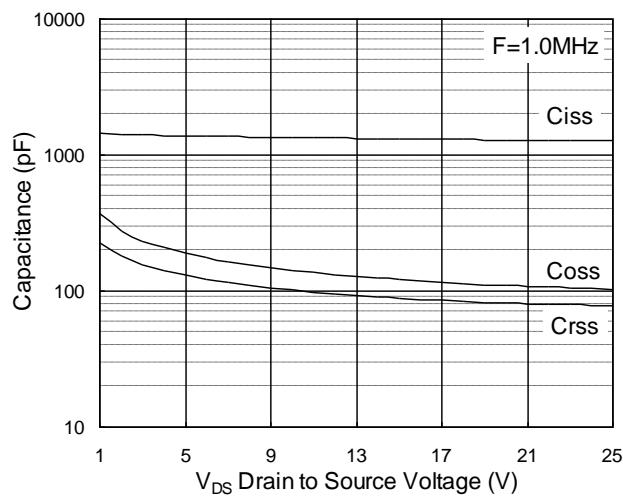


Fig.7 Capacitance

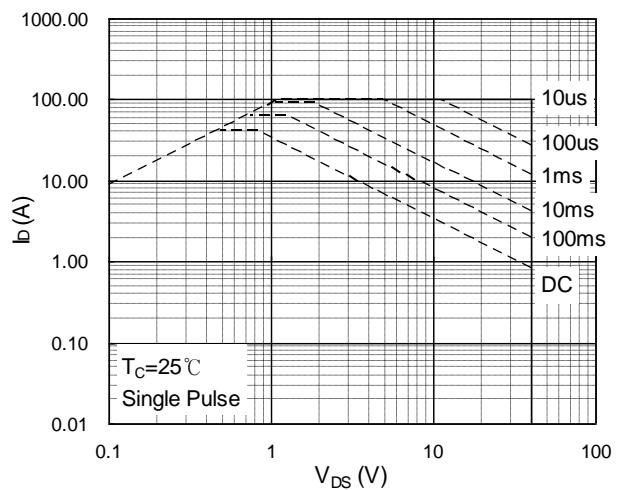


Fig.8 Safe Operating Area

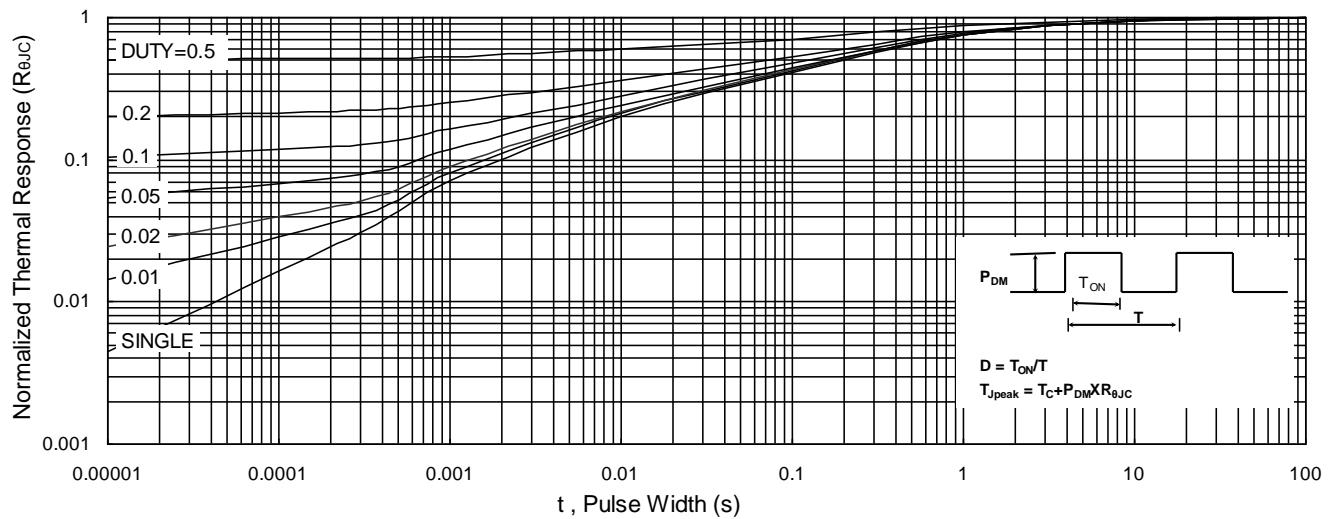


Fig.9 Normalized Maximum Transient Thermal Impedance

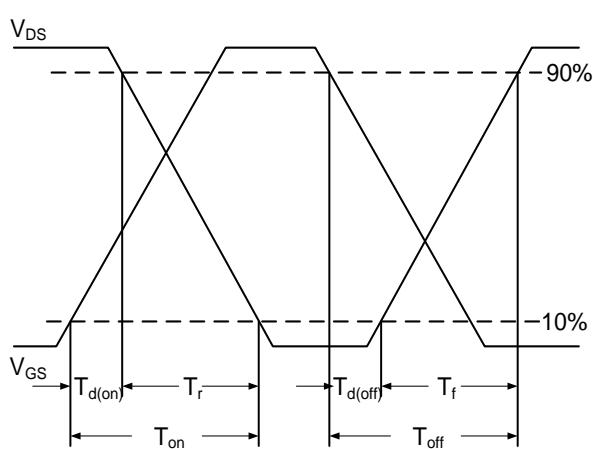


Fig.10 Switching Time Waveform

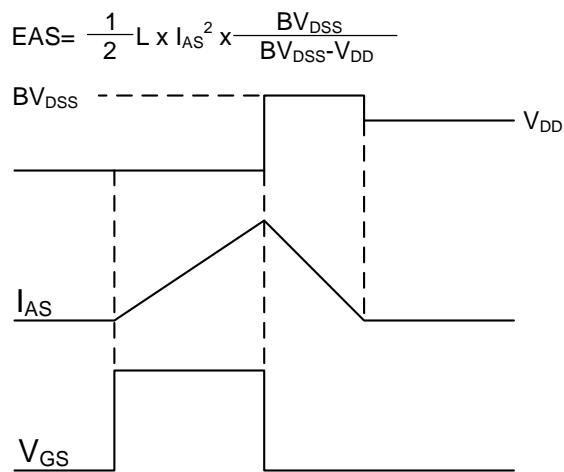


Fig.11 Unclamped Inductive Switching Waveform

P-Typical Characteristics

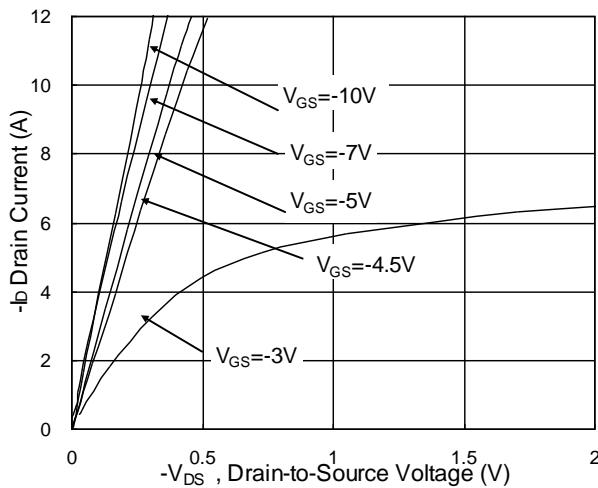


Fig.1 Typical Output Characteristics

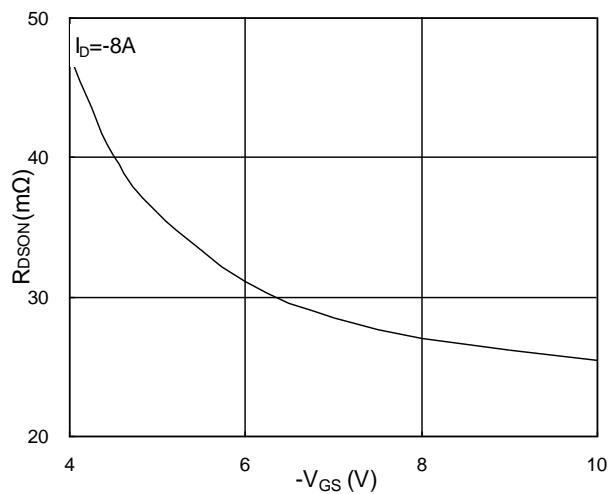


Fig.2 On-Resistance v.s Gate-Source

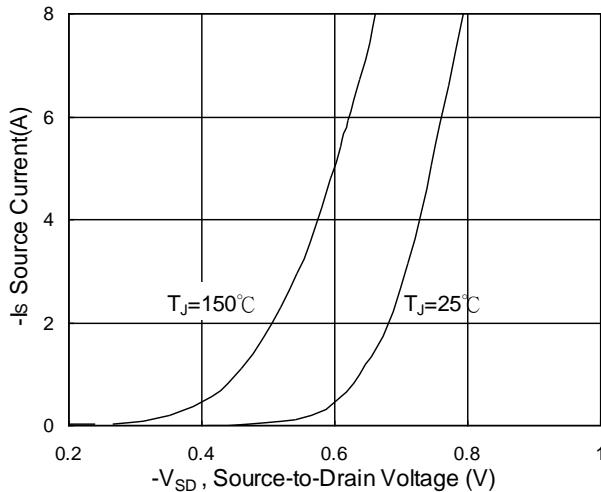


Fig.3 Forward Characteristics Of Reverse

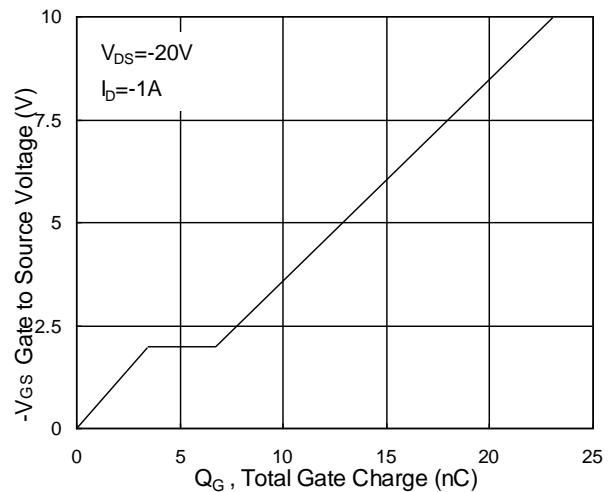


Fig.4 Gate Charge Characteristics

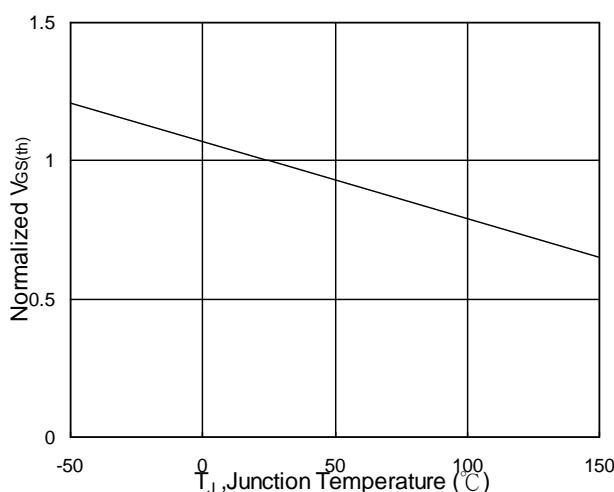


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

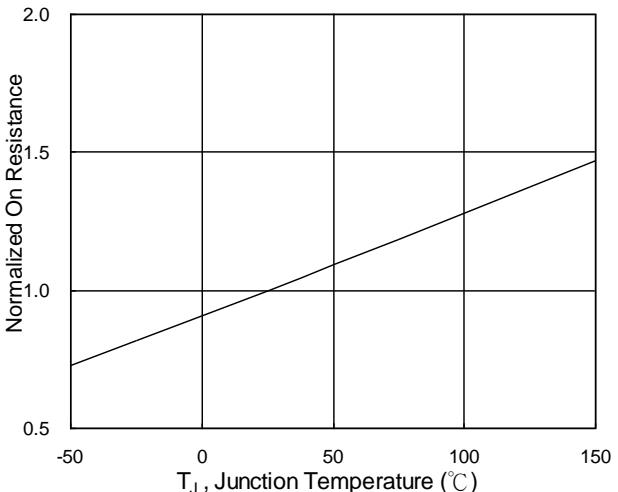


Fig.6 Normalized $R_{DS(on)}$ v.s T_J

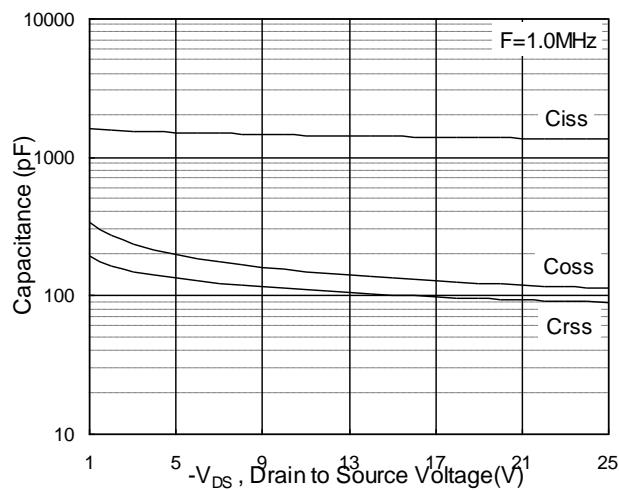


Fig.7 Capacitance

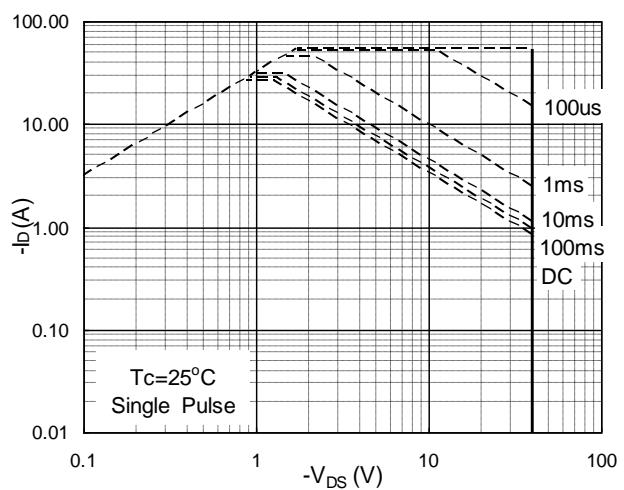


Fig.8 Safe Operating Area

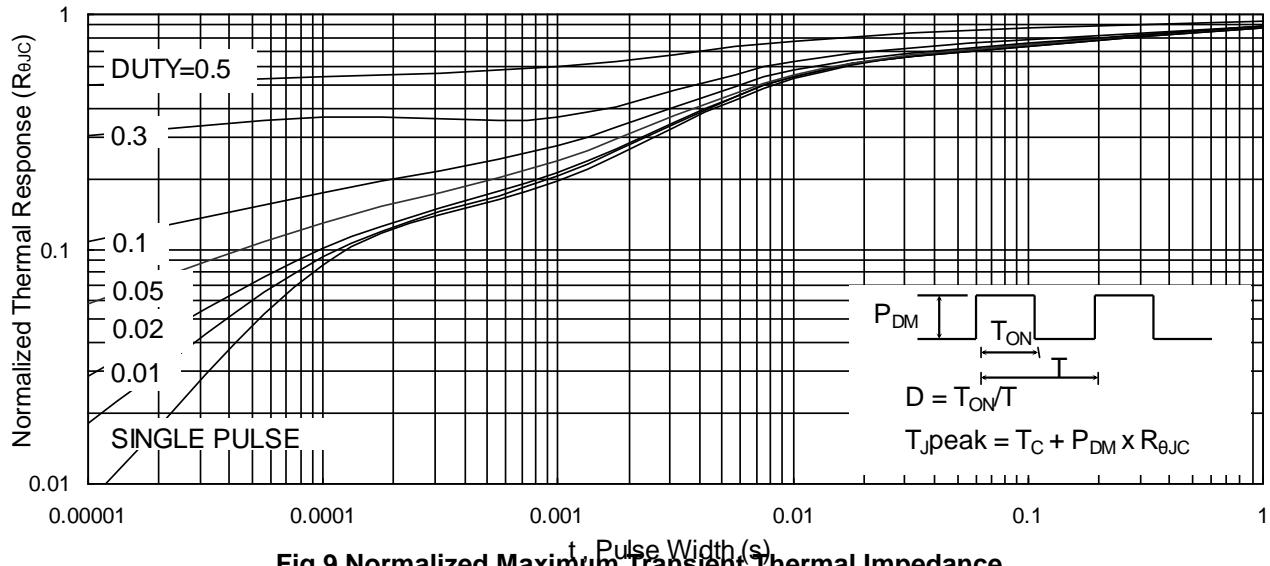


Fig.9 Normalized Maximum Transient Thermal Impedance

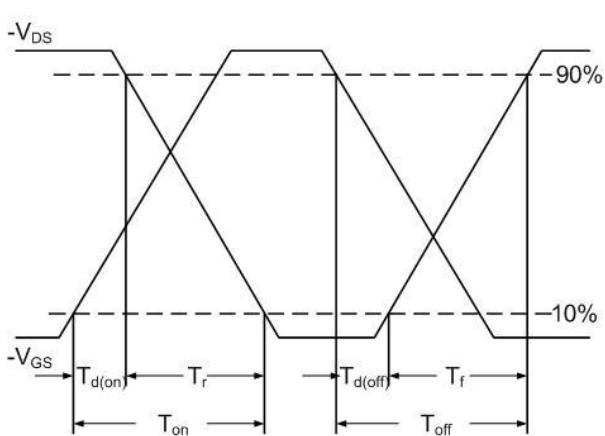


Fig.10 Switching Time Waveform

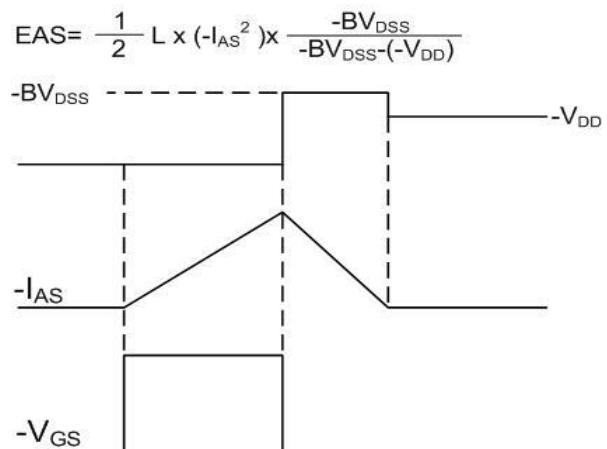
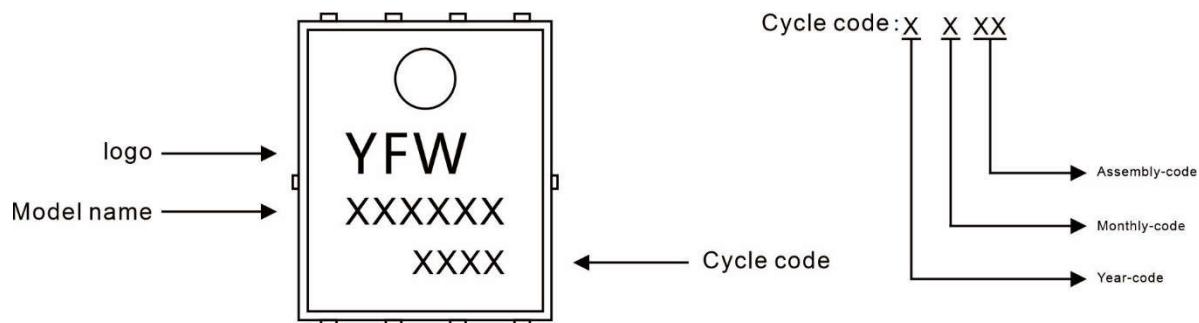


Fig.11 Unclamped Inductive Waveform

Marking Diagram

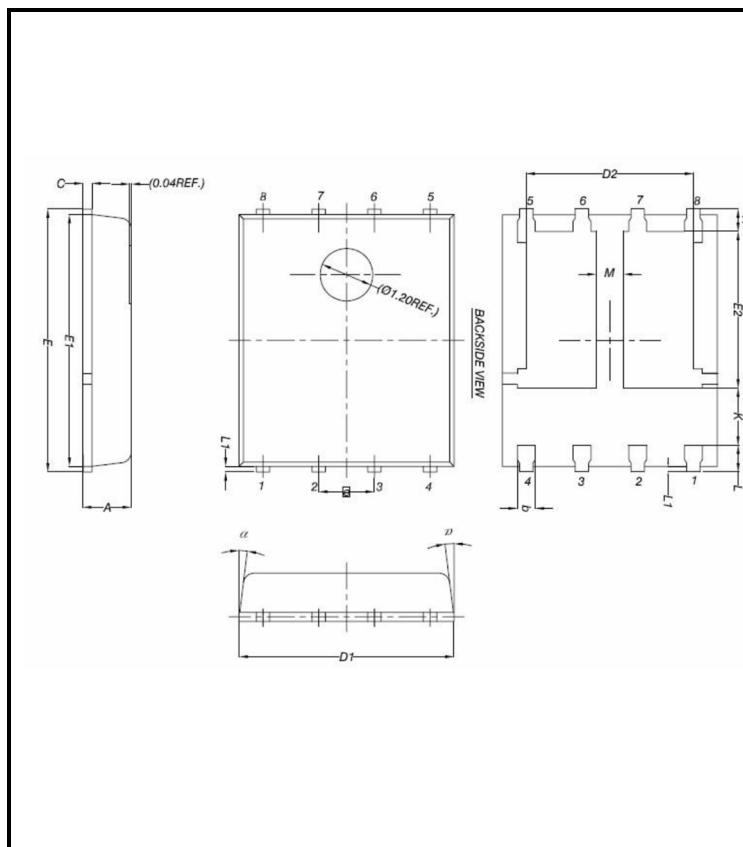


Ordering information

Model name	Package	Unit Weight	Base Quantity	Packing Quantity
YFW23G04NF	PDFN5*6-8L	0.0032oz(0.093g)	5000pcs/reel	10000pcs/box 50000pcs/Carton

Package Dimensions

PDFN5*6-8L



Dim	Millimeter		mil	
	Min.	Max.	Min.	Max.
A	0.90	1.10	35.43	43.31
b	0.33	0.51	12.99	20.08
C	0.20	0.30	7.87	11.81
D1	4.80	5.00	188.98	196.85
D2	3.61	3.96	142.13	155.91
E	5.90	6.10	232.28	240.16
E1	3.45	5.70	135.83	224.41
E2	3.05	3.38	120.08	133.07
e	1.27BSC		50BSC	
H	0.41	0.61	16.14	24.02
K	1.10	-	43.31	-
L	0.51	0.71	20.08	27.95
L1	0.06	0.20	2.46	7.87
M	0.50	-	19.69	-
a	0°	12°	0°	12°

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